APPENDIX D

(VERSION OF CLAIMS AS AMENDED HEREIN WITH MARKINGS TO SHOW CHANGES MADE)

(Serial No. 09/928,032)

VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

1. (Amended) A method of unique sequential marking a plurality of semiconductor devices in a multi-die handling device comprising:

reading an ID code on said multi-die handling device;

retrieving a tray map file corresponding to said ID code;

determining a tray matrix of said multi-die handling device;

retrieving data from the tray map file, said data comprising unique characters correlating to each semiconductor device of said plurality of semiconductor devices; and

marking each semiconductor device with said data.

6. (Amended) The method according to claim 1, wherein [said]each semiconductor device comprises an integrated circuit semiconductor device.

7. (Amended) The method according to claim 6, wherein said [integrated circuit] semiconductor device [comprises]each comprise a semiconductor device selected from the group consisting of Dynamic Random Access Memory (DRAM) semiconductor [device]devices, Static Random Access Memory (SRAM) semiconductor devices, Synchronous DRAM (SDRAM) semiconductor devices, processor semiconductor devices, Single In-Line Memory Modules ([SIMM's]SIMMs)[semiconductor devices], and Dual In-Line Memory Modules ([DIMM's]DIMMs)[semiconductor devices].

8. (Amended) The method of claim 1, wherein marking occurs before packaging [said]each semiconductor device.

9. (Amended) The method of claim 1, wherein marking occurs after packaging [said]each semiconductor device.

10. (Amended) A method of culling semiconductor devices from a reject bin, said method comprising:

retrieving a plurality of semiconductor devices from at least one reject bin;

providing at least one carrier of a plurality of carriers having a plurality of pocket locations [of a plurality of carriers];

assigning said at least one carrier of said plurality of carriers an ID code;

placing each semiconductor device of said plurality of semiconductor devices in a pocket location of said plurality of pocket locations;

testing each semiconductor device;

generating a tray map file comprising test data corresponding to each semiconductor device;

storing the tray map file in association with the ID code of said at least one carrier;

reading the ID code on said at least one carrier;

retrieving the tray map file corresponding to said ID code;

determining a tray matrix of said at least one carrier;

retrieving test data from the tray map file; and

marking each semiconductor device of said plurality of semiconductor devices with the corresponding test data.

15. (Amended) The method according to claim 10, wherein said [integrated circuit] semiconductor device [comprises]each comprise a semiconductor device selected from the group consisting of Dynamic Random Access Memory (DRAM) semiconductor devices, Static Random Access Memory (SRAM) semiconductor devices, Synchronous DRAM (SDRAM) semiconductor devices, processor semiconductor devices, Single In-Line Memory Modules ([SIMM's]SIMMs)[semiconductor devices] and Dual In-Line Memory Modules ([DIMM's]DIMMs)[semiconductor devices].

22. (Amended) The method according to claim 18, wherein said unique characters comprise test data extracted from [the]said tray map file.

23. (Amended) The method according to claim 18, wherein said at least one semiconductor device is an integrated circuit semiconductor device.

24. (Amended) The method according to claim 23, wherein said [integrated circuit] semiconductor device [comprises]each comprise a semiconductor device selected from the group consisting of Dynamic Random Access Memory (DRAM) semiconductor devices, Static Random Access Memory (SRAM) semiconductor devices, Synchronous DRAM (SDRAM) semiconductor devices, processor semiconductor devices, Single In-Line Memory Modules ([SIMM's]SIMMs)[semiconductor devices], and Dual In-Line Memory Modules ([DIMM's]DIMMs)[semiconductor devices].

25. (Amended) (The method of claim 18, wherein marking occurs before packaging said at least one semiconductor device.

26. (Amended) The method of claim 18, wherein marking occurs after packaging said at least one semiconductor device.

27. (Amended) A method of culling semiconductor devices from a reject bin, said method comprising:

retrieving a plurality of semiconductor devices from a reject bin;

providing a plurality of carriers, each carrier having a plurality of pocket locations in a tray matrix;

assigning each carrier of said plurality of carriers an ID code;

placing each semiconductor device of said plurality of semiconductor devices in a pocket location of said plurality of pocket locations;

testing each semiconductor device;

generating a tray map file comprising test data corresponding to each semiconductor device;

storing the tray map file in association with the ID code of [the]each carrier;

reading the ID code on a carrier;

retrieving the tray map file corresponding to said ID code;

determining a tray matrix of the carrier;

retrieving test data from the tray map file; and

marking each semiconductor device of said plurality of semiconductor devices with the corresponding test data.

32. (Amended) The method according to claim 27, wherein said [integrated circuit] semiconductor device [comprises]each comprise a semiconductor device selected from the group consisting of Dynamic Random Access Memory (DRAM) semiconductor devices, Static Random Access Memory (SRAM) semiconductor devices, Synchronous DRAM (SDRAM) semiconductor devices, processor semiconductor devices, Single In-Line Memory Modules ([SIMM's]SIMMs)[semiconductor devices], and Dual In-Line Memory Modules ([DIMM's]DIMMs)[semiconductor devices].